## B2893 Board Size (mm)

## B2893 BOARD SPECIFICATIONS

1. Board Layers: 8
2. Layer Stack Order:

Layer1 (Artwork_1): Top Signal_2, 0.5 oz, diff. 100 ohms
Layer2 (Artwork_2): Power_1, P2V5, 1 oz
Layer3 (Artwork_3): Inner SIgnal_3, 0.5oz, diff. 100 ohms
Layer4 (Artwork_4): Power_2, Ground, 1oz
Layer5 (Artwork_5): Inner Signal_4, 0.5oz, diff 100 ohms
Layer6 (Artwork_6): Power_3, P1V2, 1 oz
Layer7 (Artwork_4): Power_2, Ground, 1 oz
Layer8 (Artwork_7): Bot Signal_2, 0.5 oz, diff 100 ohms

3. Apply silkscreen on both side:
   Artwork_7: Top silkscreen.
   Artwork_8: Bot silkscreen.
4. Apply solder mask over bare copper on both side:
   Artwork_9: Top solder mask
   Artwork_10: Bottom solde mask
5. Material: FR4
6. Board thickness: 0.062'' +/- 0.010.
7. TRACE IMPEDENCE: diff 100 ohms +/- 10% for all signal layers.
8. Emersion gold plating over bare copper
9. All layers mininum trace width/clearence/width = 5/5/5 mils,
10. Trace width can be adusted by matching the impedance requirement by manufacturing
11. All dimensions are in inches unless otherwise noted.

BOARD's DRILL SCHEDULE (Inch)

| DRILL SYMBOL | DRILL SIZE | COUNT | PLATED | Min/Max |
|---|---|---|---|---|
| ○ | .01 | 1353 | YES | --- |
| ⊞ | .035 | 80 | YES | --- |
| ⌀ | .041 | 3 | YES | --- |
| ⊟ | .048 | 38 | YES | --- |
| ⊖ | .13779528 | 4 | YES | --- |

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SCHM# B2892
SPEC# B2893
ASSM# B2894

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
B2893 Specification

SHEET 1 OF 1
DATE 02/01/2017
DRAWN TANG

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REV 1.0